

S/N Unknown

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Wing-Cheong Gilbert Lai et al.

Examiner: Unknown

Serial No.: Unknown

Group Art Unit: Unknown

Filed: Herewith

Docket: 303.261US3

Title: SMALL GRAIN SIZE, CONFORMAL ALUMINUM INTERCONNECTS AND  
METHOD FOR THEIR FORMATION

Jc997 U.S. PRO  
09/782498  
02/13/01

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7-10-01  
R. Atches

**INFORMATION DISCLOSURE STATEMENT**

Box Patent Application  
Commissioner for Patents  
Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for review in connection with the above-identified patent application. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner be returned to the Applicants.

In accordance with 37 C.F.R. § 1.98(d), copies of the listed documents are not provided as these references were previously cited by or submitted to the U.S. Patent Office in connection with Applicants' prior U.S. application, Serial No. 09/146,509, filed on September 3, 1998, which is relied upon for an earlier filing date under 35 U.S.C. § 120.

Applicants respectfully request consideration of these references during prosecution of the above-identified matter. The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

WING-CHEONG GILBERT LAI ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
P.O. Box 2938  
Minneapolis, MN 55402  
(612) 373-6976

Date 13 feb 01 By Janal M. Kalis  
Janal M. Kalis  
Reg. No. 37,650

"Express Mail" mailing label number: EL671638680US

Date of Deposit: February 13, 2001

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to The Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.

Form 1449*	Atty. Docket No.: 303.261US3	Serial No. Unknown
	Applicant: Wing-Cheong Gilbert Lai et al.	09/182498 pro
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)</b>	Filing Date: Herewith 01/13/01	Group: Unknown 2814

U. S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
						02/13/01

02/13/01

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**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
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**\*\*Examiner Initial**    **Document Number**    **Date**    **Country**    **Class**    **Subclass**    **Translation Yes | No**

#### **OTHER DOCUMENTS**

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TU	Fjordalice, R.W., et al., "Orientation Control of Chemical Vapor Deposition TiN Film for Barrier Applications", <u>Journal of the Electrochemical Society</u> , 143(6), pgs. 2059-2063, (June 1996)
	Lee, H., et al., "Study of Diffusion Barrier Perfomance in MOCVD TiN by Transmission Electron Microscopy", <u>Materials Research Society Symposium Proceedings</u> , 391, pgs. 205-209, (1995)
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**Examiner**

Quack

Date Considered

11/15/02

\*Substitute Disclosure Statement Form (PTO-1449)

**\*\*EXAMINER:** Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.